

In the Claims

1. (Currently Amended) A polyimide molding of thermoplastic aromatic polyimide resin, comprising a wall defining an opening at one end and closed at an opposite end, and having a depth therebetween, wherein the wall thickness is between 0.001 mm and 0.5 mm, ~~wherein a ratio of depth to opening is between 1.0 and 3.0 and~~ said thermoplastic aromatic polyimide resin has a glass transition temperature between 200°C and 350°C and has a degree of elongation of break of from 50 to 2,000% at its glass transition temperature, and wherein the polyimide molding has a plurality of repetitive patterns, ~~and wherein said molding is further defined by at least one of the following:~~

~~(a) — a ratio of depth to opening is between 0.7 and 5.0; and~~

~~(b) — a longest major axis is between 200 and 10,000 mm in length with a depth between 0.5 and 8,000 mm.~~

2. (Cancelled)

3. (Currently Amended) The polyimide molding as claimed in claim 1, wherein the wall thickness falls between 0.01 and 0.2 mm, ~~and wherein said molding is further defined by at least one of the following:~~

~~a ratio of depth to opening falls between 1.0 and 3.0; and~~

~~the longest major axis falls between 200 and 5000 mm in length with a depth falling between 1.0 and 2000 mm.~~

Claims 4– 9 (Cancelled)

10. (New) The polyimide molding as claimed in claim 1, wherein the repetitive patterns are tray-shaped, carrier belt-shaped or cup container-shaped.

11. (New) The polyimide molding as claimed in claim 1, wherein the glass transition point is between 220 and 300°C.

12. (New) The polyimide molding as claimed in claim 1, wherein the elongation at break is from 300 to 800%.

13. (New) The polyimide molding as claimed in claim 1, wherein the polyimide resin is a condensate of a carboxylic acid anhydride and a diamine.

14. (New) The polyimide molding as claimed in claim 13, wherein the carboxylic acid anhydride is selected from the group consisting of pyromellitic acid dianhydride, 4,4'-hydroxydiphthalic acid dianhydride, 3,3',4,4'-benzophenonetetracarboxylic acid dianhydride, 2,2',3,3'-benzophenonetetracarboxylic acid dianhydride, 3,3',4,4'-biphenyltetracarboxylic acid dianhydride, 2,2',3,3'-biphenyltetracarboxylic acid dianhydride, 2,2-bis(3,4-dicarboxyphenyl) hexafluoropropane dianhydride, bis(3,4-dicarboxyphenyl) sulfone dianhydride, bis(3,4-dicarboxyphenyl) sulfide dianhydride, bis(2,3-dicarboxyphenyl) methane dianhydride, bis(3,4-dicarboxyphenyl) methane dianhydride, 1,1-bis(2,3-dicarboxyphenyl) propane dianhydride, 2,2-bis(3,4-dicarboxyphenyl) propane dianhydride, and m-phenylenebis (trimellitic acid) dianhydride.

15. (New) The polyimide molding as claimed in claim 13, wherein the diamine is selected from the group consisting of hexamethylenediamine, heptamethylenediamine, 3,3'-dimethylpentamethylenediamine, 3-methylhexamethylenediamine, 3-methylheptamethylenediamine, 2,5-dimethylhexamethylenediamine, octamethylenediamine, nonamethylenediamine, 1,1,6,6-tetramethylhexamethylenediamine, 2,2,5,5-tetramethylhexamethylenediamine, 4,4-dimethylheptamethylenediamine, decamethylenediamine, m-phenylenediamine, 4,4'-diaminobenzophenone, 4-aminophenyl 3-aminobenzoate, m-aminobenzoyl-p-aminoanilide, 4,4'-diaminodiphenyl ether, 3,4'-diaminodiphenyl ether, bis(4-aminophenyl) methane, 1,1-bis(4-aminophenyl) ethane, 2,2-bis(4-

aminophenyl propane, 4,4'-diaminodiphenyl sulfoxide, 3,3'-diaminobenzophenone, 1,3-bis(4-aminophenoxy) benzene, 2,2'-diaminobenzophenone, 1,2-bis(4-aminophenoxy) benzene, 1,3-bis(4-aminobenzoyloxy) benzene, 4,4'-diaminobenzanilide, 4,4'-bis(4-aminophenoxy) phenyl ether, 2,2'-bis(4-aminophenyl) hexafluoropropane, 2,2'-bis(4-aminophenyl)-1,3-dichloro-1,1,3,3-tetrafluoropropane, 4,4'-diaminodiphenyl sulfone, 1,12-diaminododecane, 1,13-diaminododecane, and polysiloxanediamine.